WHAT IS CLAIMED IS:

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1. A method of manufacturing a light emitting device having a light emitting element composed of an anode, a cathode, and an organic compound layer, comprising the steps of:

applying a reverse bias to the light emitting element; determining fault portions of the light emitting element; and irradiating a laser to the fault portions.

2. A method of manufacturing a light emitting device having a light emitting element composed of an anode, a cathode, and an organic compound layer, comprising the steps of:

applying a reverse bias to the light emitting element;

determining fault portions of the light emitting element by detecting light emitting positions; and

irradiating a laser to the fault portions.

- 3. A method of manufacturing a light emitting device having a light emitting element composed of an anode, a cathode, and an organic compound layer, comprising the steps of:
- applying a reverse bias to the light emitting element;

 determining fault portions of the light emitting element; and

 irradiating a laser to the fault portions, making the fault portions insulating.
 - 4. A method of manufacturing a light emitting device having a light emitting

element composed of an anode, a cathode, and an organic compound layer, comprising the steps of:

applying a reverse bias to the light emitting element;

determining fault portions of the light emitting element by detecting light emitting positions; and

irradiating a laser to the fault portions, making the fault portions insulating.

5. A method of manufacturing a light emitting device having a light emitting element composed of an anode, a cathode, and an organic compound layer, comprising the steps of:

applying a reverse bias to the light emitting element;

determining fault portions of the light emitting element; and

irradiating a laser to the fault portions, making inverse direction electric current flow smaller than before the laser irradiation.

6. A method of manufacturing a light emitting device having a light emitting element composed of an anode, a cathode, and an organic compound layer, comprising the steps of:

applying a reverse bias to the light emitting element;

determining fault portions of the light emitting element by detecting light emitting positions; and

irradiating a laser to the fault portions, making inverse direction electric current flow smaller than before the laser irradiation.

- 7. A method of manufacturing a light emitting device according to claim 1, wherein the organic compound layer contacts the cathode, and the anode contacts the organic compound layer.
- 8. A method of manufacturing a light emitting device according to claim 2, wherein the organic compound layer contacts the cathode, and the anode contacts the organic compound layer.
- 9. A method of manufacturing a light emitting device according to claim 3, wherein the organic compound layer contacts the cathode, and the anode contacts the organic compound layer.
- 10. A method of manufacturing a light emitting device according to claim 4, wherein the organic compound layer contacts the cathode, and the anode contacts the organic compound layer.
- 11. A method of manufacturing a light emitting device according to claim 5, wherein the organic compound layer contacts the cathode, and the anode contacts the organic compound layer.
- 12. A method of manufacturing a light emitting device according to claim 6, wherein the organic compound layer contacts the cathode, and the anode contacts the organic compound layer.

- 13. A method of manufacturing a light emitting device according to claim 1, wherein the organic compound layer comprises light emitting layers, hole injecting layers, hole transporting layers, electron transporting layers, and electron injecting layers.
- 14. A method of manufacturing a light emitting device according to claim 2, wherein the organic compound layer comprises light emitting layers, hole injecting layers, hole transporting layers, electron transporting layers, and electron injecting layers.
- 15. A method of manufacturing a light emitting device according to claim 3, wherein the organic compound layer comprises light emitting layers, hole injecting layers, hole transporting layers, electron transporting layers, and electron injecting layers.
- 16. A method of manufacturing a light emitting device according to claim 4, wherein the organic compound layer comprises light emitting layers, hole injecting layers, hole transporting layers, electron transporting layers, and electron injecting layers.
- 17. A method of manufacturing a light emitting device according to claim 5, wherein the organic compound layer comprises light emitting layers, hole injecting layers, hole transporting layers, electron transporting layers, and electron injecting layers.
- 18. A method of manufacturing a light emitting device according to claim 6, wherein the organic compound layer comprises light emitting layers, hole injecting layers, hole transporting layers, electron transporting layers, and electron injecting layers.

- 19. A method of manufacturing a light emitting device according to claim 1, further having at least a thin film transistor.
- 5 20. A method of manufacturing a light emitting device according to claim 2, further having at least a thin film transistor.
 - 21. A method of manufacturing a light emitting device according to claim 3, further having at least a thin film transistor.
 - 22. A method of manufacturing a light emitting device according to claim 4, further having at least a thin film transistor.

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- 23. A method of manufacturing a light emitting device according to claim 5, further having at least a thin film transistor.
- 24. A method of manufacturing a light emitting device according to claim 6, further having at least a thin film transistor.
- 25. A method of manufacturing a light emitting device according to claim 1, wherein the reverse bias is applied in a range of 1 to 15 V.
 - 26. A method of manufacturing a light emitting device according to claim 2, wherein the reverse bias is applied in a range of 1 to 15 V.

- 27. A method of manufacturing a light emitting device according to claim 3, wherein the reverse bias is applied in a range of 1 to 15 V.
- 28. A method of manufacturing a light emitting device according to claim 4, wherein the reverse bias is applied in a range of 1 to 15 V.
- 29. A method of manufacturing a light emitting device according to claim 5, wherein the reverse bias is applied in a range of 1 to 15 V.
- 30. A method of manufacturing a light emitting device according to claim 6, wherein the reverse bias is applied in a range of 1 to 15 V.
 - 31. A thin film forming apparatus comprising:
- a first film formation chamber for forming an organic compound layer of a light emitting element;
- a second film formation chamber for forming an opposing electrode of the light emitting element;
- a first processing chamber for applying a reverse bias to the light emitting element, detecting light emission locations of the light emitting element;
 - a second processing chamber for irradiating a laser to the light emitting element; and a third processing chamber for sealing a light emitting device.
 - 32. A thin film forming apparatus according to claim 31, wherein the first film

formation chamber is a film formation chamber for performing film formation by an evaporation method, or a film formation chamber for performing film formation by an application method.

- 33. A thin film forming apparatus according to claim 31, wherein the first processing chamber has: a means for applying a reverse bias within a range of 1 to 15 V to the light emitting element; and a means for detecting the light emission locations.
- 34. A method of manufacturing a light emitting device using the thin film forming apparatus according to claim 31, comprising the steps of:

detecting the light emission locations in the first processing chamber;

irradiating the laser to the light emission locations in the second processing chamber;

and

sealing the light emitting element in the third processing chamber.

35. A method of manufacturing a light emitting device according to claim 1, wherein the light emitting device is at least one device selected from the group consisting of: a digital still camera, a laptop computer, a mobile computer, a DVD player, a goggle type display, a video camera and a cellular phone.

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36. A method of manufacturing a light emitting device according to claim 2, wherein the light emitting device is at least one device selected from the group consisting of: a digital still camera, a laptop computer, a mobile computer, a DVD player, a goggle type display, a video camera and a cellular phone.

- 37. A method of manufacturing a light emitting device according to claim 3, wherein the light emitting device is at least one device selected from the group consisting of: a digital still camera, a laptop computer, a mobile computer, a DVD player, a goggle type display, a video camera and a cellular phone.
- 38. A method of manufacturing a light emitting device according to claim 4, wherein the light emitting device is at least one device selected from the group consisting of: a digital still camera, a laptop computer, a mobile computer, a DVD player, a goggle type display, a video camera and a cellular phone.
- 39. A method of manufacturing a light emitting device according to claim 5, wherein the light emitting device is at least one device selected from the group consisting of: a digital still camera, a laptop computer, a mobile computer, a DVD player, a goggle type display, a video camera and a cellular phone.
- 40. A method of manufacturing a light emitting device according to claim 6, wherein the light emitting device is at least one device selected from the group consisting of: a digital still camera, a laptop computer, a mobile computer, a DVD player, a goggle type display, a video camera and a cellular phone.